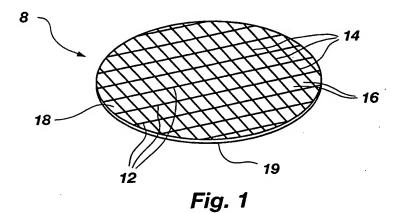
TITLE: SEMICONDUCTOR DEVICES INCLUDING PERIPHERALLY LOCATED BOND PADS, INTERMEDIATES THEREOF, ASSEMBLIES, AND PACKAGES INCLUDING THE SEMICONDUCTOR DEVICES, AND SUPPORT ELEMENTS FOR THE SEMICONDUCTOR DEVICES

Inventor: Poo et al. Docket No.: 2269-4885.1US

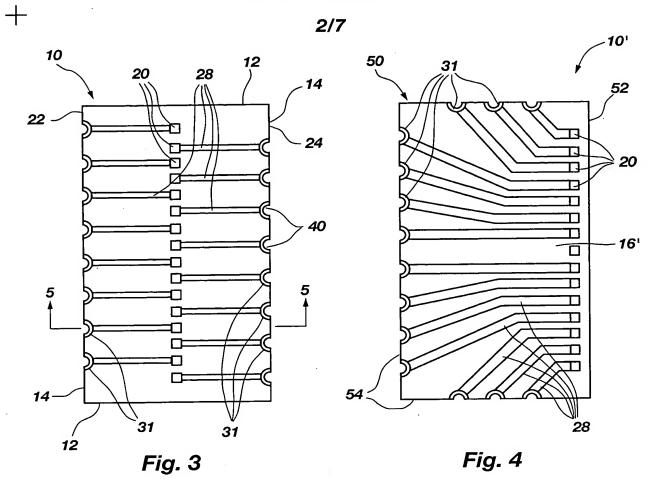


14C 14B 12A 18 30C 14A 20 38 10B <u>10C</u> 10A <u>10F</u> 10E <u>10D</u> 口 ₫ O  $\Box$ <u>10J</u> <u>10G</u> <u>10H</u> 30A 28 12B 30B

Fig. 2

TITLE: SEMICONDUCTOR DEVICES INCLUDING PERIPHERALLY LOCATED BOND PADS, INTERMEDIATES THEREOF, ASSEMBLIES, AND PACKAGES INCLUDING THE SEMICONDUCTOR DEVICES, AND SUPPORT ELEMENTS FOR THE SEMICONDUCTOR DEVICES

Inventor: Poo et al. Docket No.: 2269-4885.1US



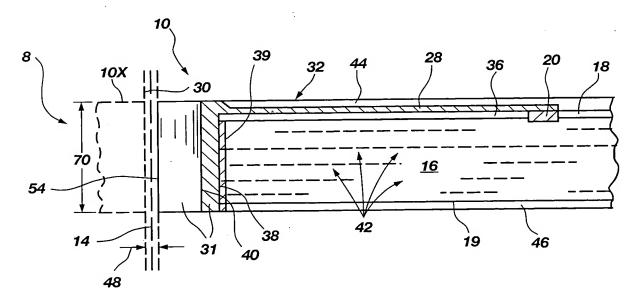
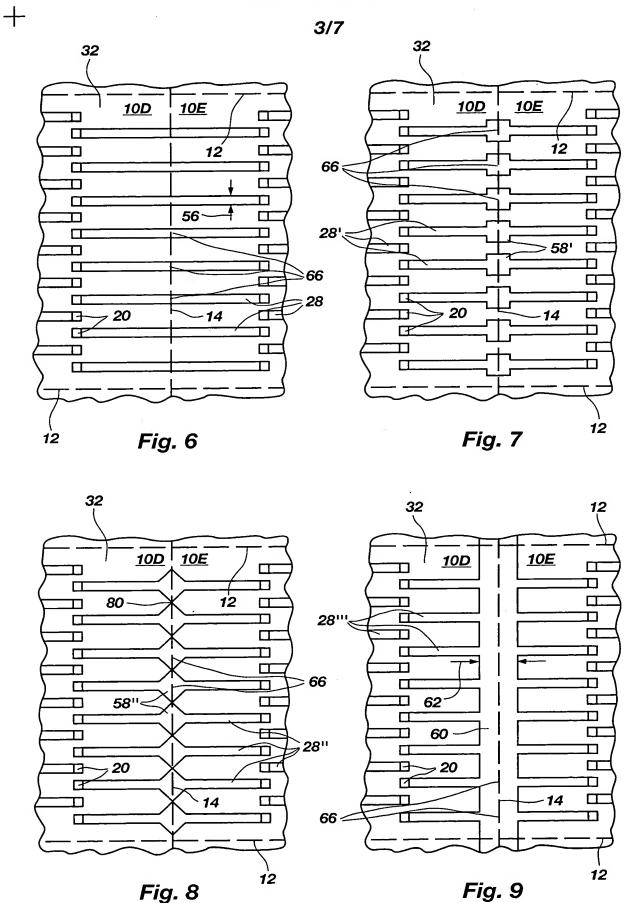
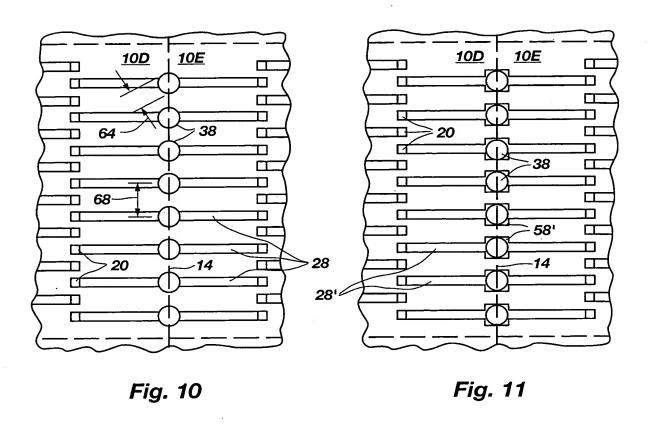


Fig. 5

Inventor: Poo et al. Docket No.: 2269-4885.1US



Inventor: Poo et al. Docket No.: 2269-4885.1US



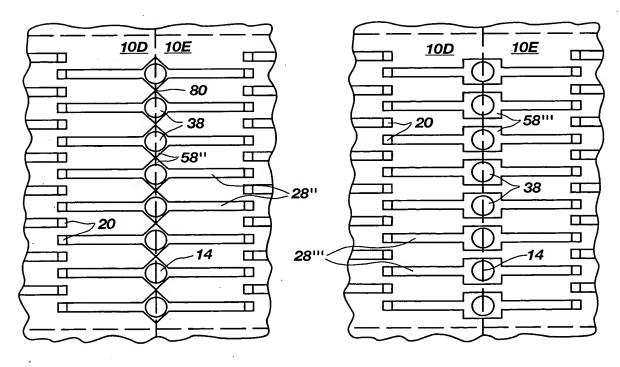


Fig. 12

Fig. 13

TITLE: SEMICONDUCTOR DEVICES INCLUDING PERIPHERALLY LOCATED BOND PADS, INTERMEDIATES THEREOF, ASSEMBLIES, AND PACKAGES INCLUDING THE SEMICONDUCTOR DEVICES, AND SUPPORT ELEMENTS FOR THE SEMICONDUCTOR DEVICES

Inventor: Poo et al. Docket No.: 2269-4885.1US

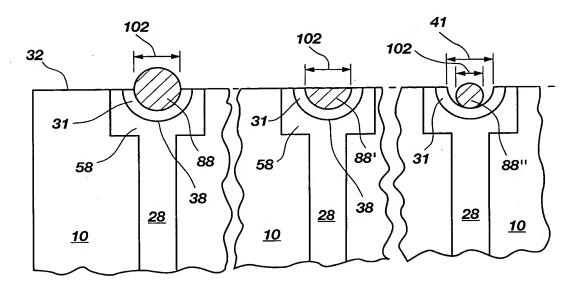


Fig. 20

Fig. 21

Fig. 22

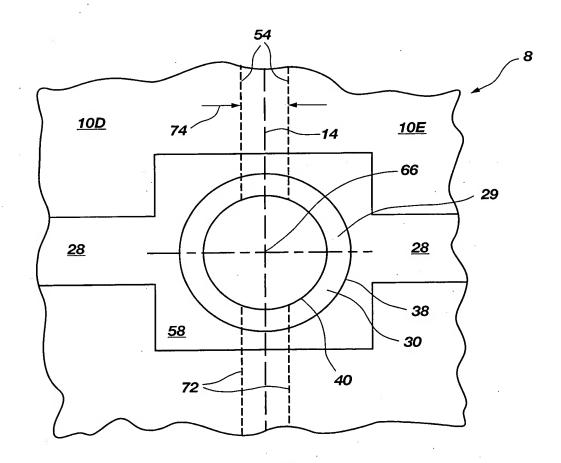
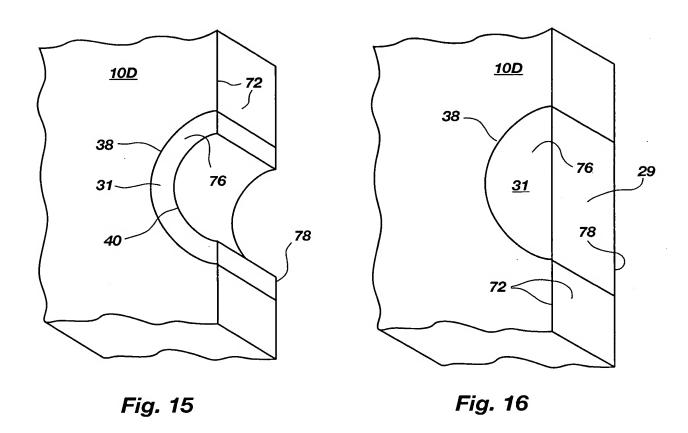


Fig. 14

Inventor: Poo et al.
Docket No.: 2269-4885.1US



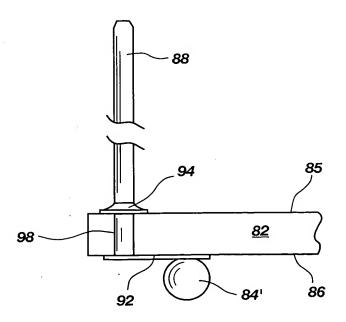
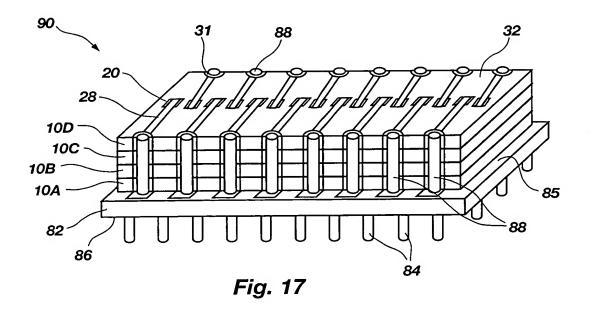


Fig. 19

TITLE: SEMICONDUCTOR DEVICES INCLUDING PERIPHERALLY LOCATED BOND PADS, INTERMEDIATES THEREOF, ASSEMBLIES, AND PACKAGES INCLUDING THE SEMICONDUCTOR DEVICES, AND SUPPORT ELEMENTS FOR THE SEMICONDUCTOR DEVICES Inventor: Poo et al.

Docket No.: 2269-4885.1US



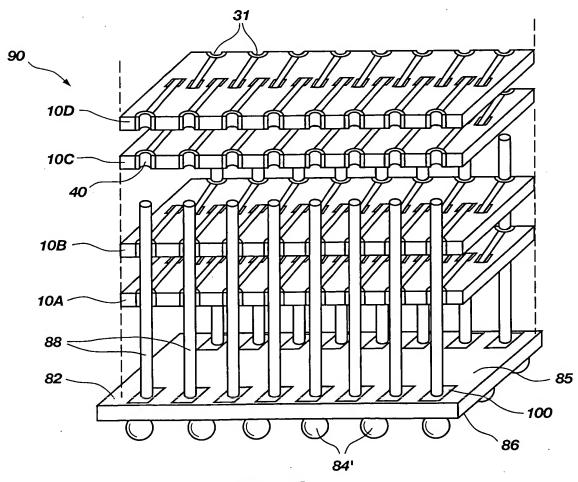


Fig. 18